

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-16V	28m $\Omega$ @-4.5V	-6A
	38m $\Omega$ @-2.5V	

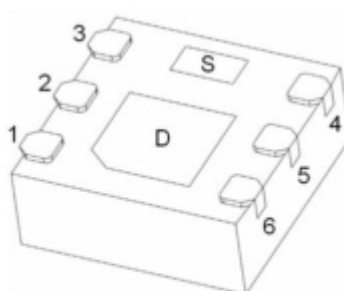
## Feature

- TrenchTechnology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package DFN2\*2-6L

## Applications

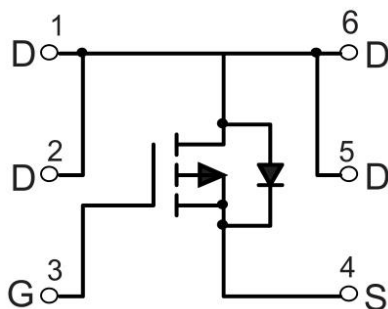
- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

## Package

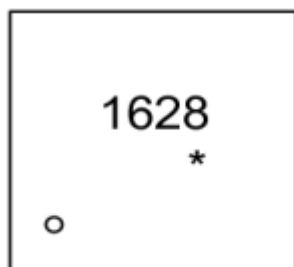


DFNWB2\*2-6L-J

## Circuit diagram



## Marking



1628      =Device Code  
\*            =Month Code

## Absolute maximum ratings

(T<sub>a</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source Voltage	V <sub>DS</sub>	-16	V
Gate-source Voltage	V <sub>GS</sub>	±10	V
Drain Current	I <sub>D</sub>	-6	A
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub>	-24	A
Total Power Dissipation @ T <sub>C</sub> =25°C	P <sub>D</sub>	1.4	W
Thermal Resistance Junction-to-Case @ Steady State	R <sub>θJC</sub>	88	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG.</sub>	-55~ +150	°C

## Electrical characteristics

( $T_A=25^{\circ}\text{C}$ , unless otherwise noted)

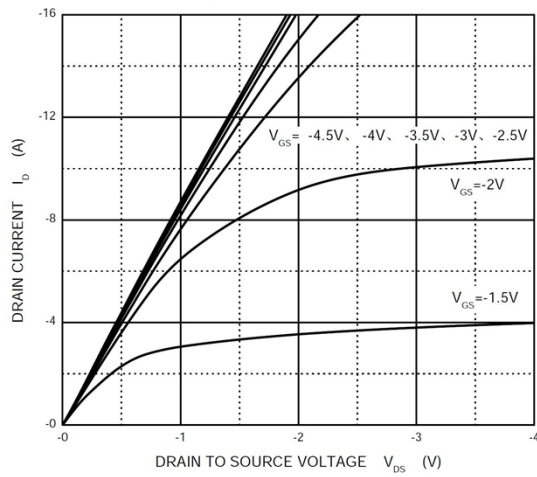
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV (BR)DSS	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-16			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, T <sub>C</sub> =25°C			-1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±10V, V <sub>DS</sub> = 0V			±100	μA
Gate threshold voltage <sup>(1)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.5A		28	35	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3A		38	45	
Dynamic Characteristics						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -4V, V <sub>GS</sub> =0V, f=1MHz		740		pF
Output capacitance	C <sub>oss</sub>			290		
Reverse transfer capacitance	C <sub>rss</sub>			190		
Switching Parameters						
Total gate charge	Q <sub>g</sub>	V <sub>GS</sub> = -4.5V , V <sub>DS</sub> = -2.5V , I <sub>D</sub> = -4.1A		4.5		nC
Gate-source charge	Q <sub>gs</sub>			1.2		
Gate-drain charge	Q <sub>gd</sub>			1.6		
Turn-on Delay Time	T <sub>d(on)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -4V, R <sub>L</sub> =1.2Ω ,R <sub>G</sub> =1Ω		13		nS
Turn-on Rise Time	T <sub>r</sub>			35		
Turn-Off Delay Time	T <sub>d(off)</sub>			32		
Turn-Off Fall Time	t <sub>f</sub>			10		
Source-Drain Diode Characteristics						
Diode Forward voltage	V <sub>DS</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> = -1A			-1.2	V

### Notes :

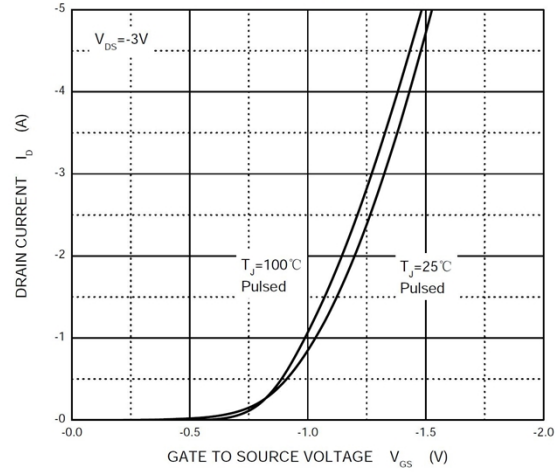
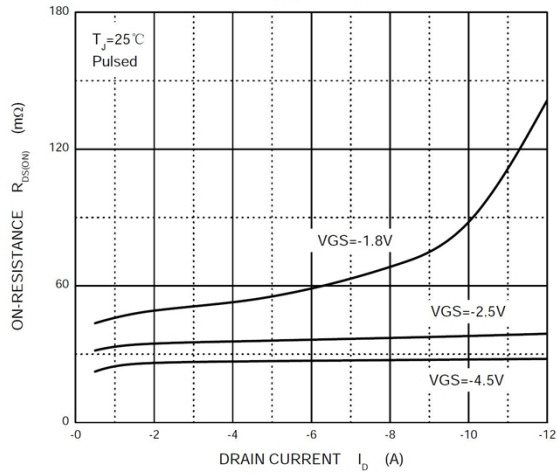
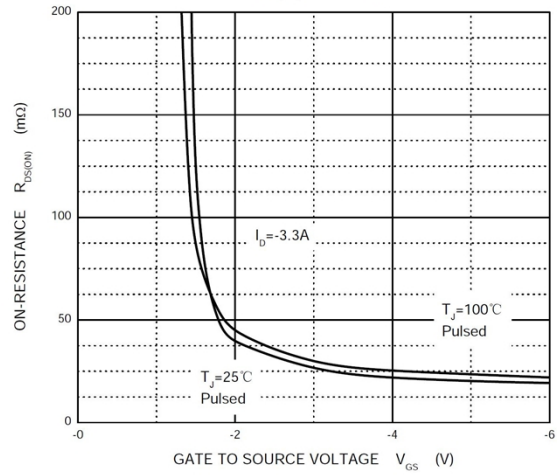
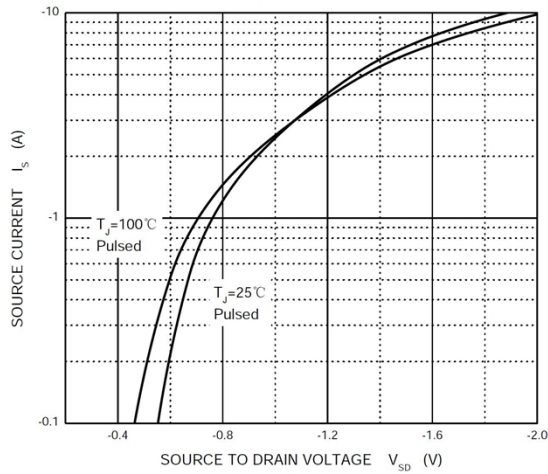
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

## Typical Characteristics

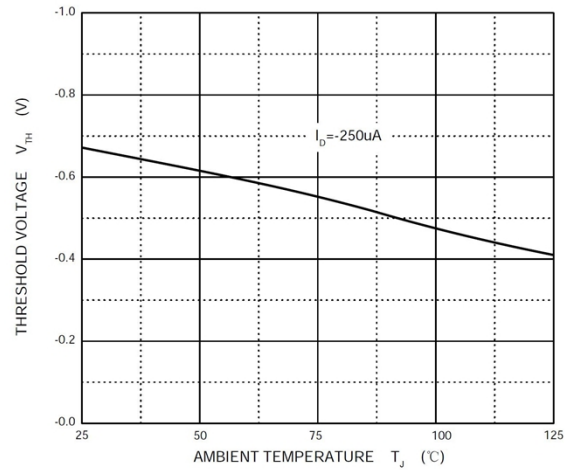
Output Characteristics



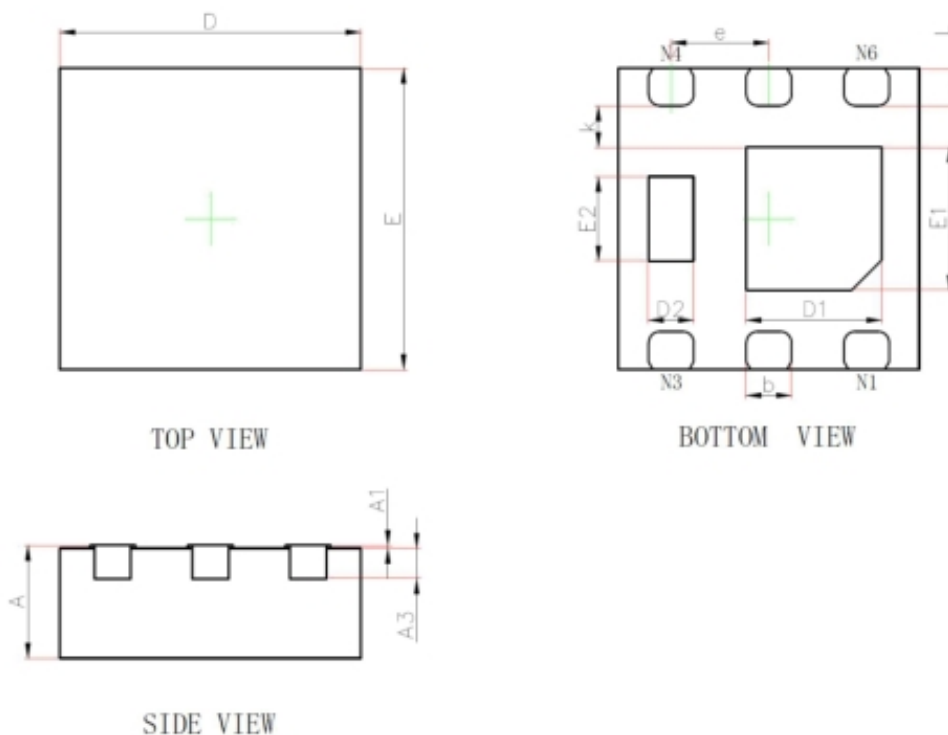
Transfer Characteristics


 $R_{DS(ON)}$  —  $I_D$ 

 $R_{DS(ON)}$  —  $V_{GS}$ 

 $I_S$  —  $V_{SD}$ 


Threshold Voltage



## DFN2\*2-6L-J Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.032
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013